

# EPIGAP Optronik GmbH

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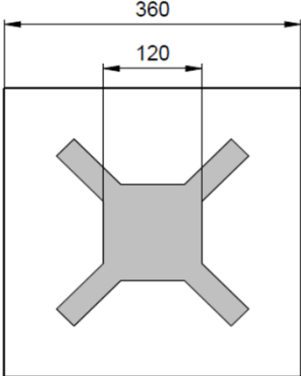
## Data Sheet

### LED Chip Infrared

### EOLC-870-17-2

Rev. 03, 2017

Radiation	Type	Electrodes
Infrared	AlGaAs/AlGaAs, DDH	P (anode) up

	<b>typ. dimensions (μm)</b>
	typ. thickness: 200±25 μm anode: gold alloy, thickness 1.5 μm cathode: gold alloy, thickness 0.5 μm, structured, 25% covered

### Optical and Electrical Characteristics

T<sub>amb</sub> = 25°C, unless otherwise specified

Parameter	Test cond.	Symbol	Min	Typ	Max	Unit
Forward voltage	I <sub>F</sub> =20 mA	V <sub>F</sub>		1.35	1.6	V
Reverse voltage	I <sub>R</sub> =100 μA	V <sub>R</sub>	5			V
Radiant power*	I <sub>F</sub> =20 mA	Φ <sub>e</sub>	4	6		mW
Radiant power**	I <sub>F</sub> =20 mA	Φ <sub>e</sub>		11		mW
Peak wavelength	I <sub>F</sub> =20 mA	λ <sub>p</sub>	855	870	880	nm
FWHM	I <sub>F</sub> =20 mA	Δλ <sub>0.5</sub>		45		nm
Switching time	I <sub>F</sub> =20 mA	t <sub>r</sub> , t <sub>f</sub>		25		ns

\*Measured on bare chip on TO-18 header

\*\*Measured on epoxy covered chip on TO-18 header

### Packing

Chips on adhesive film with wire-bond side top

Art. No. 113 006



We reserve the right to make changes to improve technical design and may do so without further notice. Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer.